Product Specification 108-60038 CHAMP .050(I) Board-to-Board Connector Lead Free Version

- 1. Scope:
- 1.1 Contents:

This specification covers the requirements for product performance, test methods and quality

assurance provisions of CHAMP .050 (I) Board-to-Board Connector.

The applicable product description and part numbers are as shown in Fig. 1:

2. Applicable Documents

The following documents form a part of this specification to the extent specified herein. In the event of conflict between the requirements this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements this specification and referenced documents, this specification shall take precedence.

2.1 AMP Specifications:

A. 109-5000: Test Specification, General Requirements for Test Methods

B. 501-60009: Test Report (Dip Type)

2.2 Military Standard and Specifications:

MIL-STD-202 Test Methods for Electronic and Electrical Component Parts



- 3. Requirements:
- 3.1 Design and Construction:

Product shall be of the design, construction and physical dimensions specified in the applicable Product drawing.

3.2 Materials: A. Conta

Contact:	Phosphor Bronze

1. 3 µm minimum thick nickel underplate

 $0.2~\mu\text{m}, 0.5~\mu\text{m}$ and $0.76~\mu\text{m}$ minimum thick gold-plated on contact area

only.

 $1.0 \ \mu m$ minimum thick solder-plated on tine area only.

- B. Housing and Tine Plate: Molded Thermoplastic
- C. Accessories and Hardware:

Retention Leg: Brass

1 µm minimum thick nickel underplate

2 µm minimum thick solder-plated

3.3 Ratings:

А.	Voltage Rating:	250	VAC

- B.Current Rating:1 A
- C. Temperature Rating: -55°C~85°C
- 3.4 Performance and Test Descriptions:

The product shall be designed to meet the electrical, mechanical and environmental performance requirements specified in Fig. 1. All tests shall be performed in the room temperature unless otherwise specified.

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Pare.	Test Items	Requirements	Procedures
3.5.1	Confirmation of Product	Product shall be conforming to the requirements of a applicable product drawing,	Visually, dimensionally and functionally inspected per applicable inspections plan.
Electric	al Requirements		
3.5.2	Termination Resistance (Low Level)	35 mΩ max.(Initial) $\Delta R=20$ mΩ max.(Final)	Subject mated contacts assembled in housing to closed circuit of 50 mA max. at open circuit voltage of 50 mV max. Fig.3.
			AMP Spec. 109-5306
3.5.3	Insulation Resistance	1,000 MΩ MIN. (Initial) 100 MΩ Min. (Final)	Measure by applying test potential between the adjacent contacts, and between the contacts and ground in the mated connector. MIL-STD-202, Method 302,Condition B
3.5.4	Dielectric Strength	Connector must withstand test potential of 0.5 KVAC for 1 minute. Current leakage must be 0.5mA max.	Measure by applying test potential between the adjacent contacts, and between the contacts and ground in the mated connectors. MIL-STD-202, Method 301
3.5.5	Temperature Rising vs. Curent	30°C max. under loaded specified current.	Measure temperature rising by energized current. Fig.3. AMP Spec.109-5310

3.5 Test Requirements and Procedures Summary

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Para.	Test Items	R	equireme	ents	Procedures			
		Phys	Physical Requirements					
3.5.6	Vibration Sinusoidal Low Frequency	No electr greater th (s) shall c	an 1 mici		Subject mated connectors to 10-55- 10 Hz traversed in 1 minute at 1.52 mm amplitude 2 hours each of 3 mutually perpendicular planes.			
3.5.7	Physical Shock	No electr greater th (s) shall c	an 1 mici		MIL-STD-202, Method 3 Subject mated connector halfsine shock pulses of millisecond duration:3 sh each direction applied al mutually perpendicular p totally 18shocks;MIL-ST 202,Method 213,Conditi	s to 50 G 11 locks in ong the 3 planes TD-		
3.5.8	Connector Mating Force	90 g max	. per cont	act	Using autograph, measur required to mate connect locking latch by operatin mm a minute. Calculate t for a contact. AMP Spec	or using g at 100 the value		
3.5.9	Connector Unmating Force	15 g min.	15 g min. per contact The requirements per Para.3.5.2 shall be met.		Using autograph, measure the force required to unmate connector without locking latch set in effect, by operating at 100 mm a minute. Calculate value for a contact. AMI Spec. 109-5206			
3.5.10	Durability (Repeated Mate/Unmating)				Mate and unmate connectors for 500 cycles at a maximum rate of 40 cycles minute. AMP Spec. 109-27			
3.5.11	Solderability	Solderable area shall have a solder coverage of 95% minimum.			With the connector mounted on PCB. immerse in melted solderin tub so that the lower surface of F get wetted in the temperature of 230°C±5°C PCB for 5 seconds.			
		Fig.1 (T	`o be cont	inued)				
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Para.	Test items	Req	uirement	S	Procedures			
3.5.12	Resistance to Soldering Heat (Dip Type)	No physica occur.	al damage	shall	Subject connector mounted on printed circuit boards to solder bath at 260±5°C for 5 seconds. MIL-STD-202, Method 210 except as indicated above			
3.5.13 Thermal Shock		The requirements per Para. 3.5.2 shall be met.		er Para.	Subject mated connectors to 5 cycles between -55 +0/-3 °C and +85 +3/-0 °C. MIL-STD-202, Method 107,Condition A			
3.5.14 Humidity- Temperature Cyclin		The requir Paras.3.5.2 3.5.4 shall	2, 3.5.3, a		Subject mated connectors to cycles of humidity-temperatu changes between 25°C and 6 95% R.H.	ire		
3.5.15	Salt Spay	The requir 3.5.2 shall	_	er Para.	Subject mated connectors to concentration for 48 hours;	5% salt		
					MIL-STD-202, Method 101 Condition B.			
3.5.16	Temperature Life	The requir 3.5.2 shall	-	er Para.	Subject mated connectors to temperature life;85°C±2°C, 2 hours MIL-STD-202, Method 108	250	-	
3.5.17	Sulfurous acid gas	The requir 3.5.2 shall	-	er Para.	Condition B. Subject mated connectors to sulfurous acid gas of 10±3pp concentration in the room temperature with 90% min. F 48 hours.		-	
			Fig.1 (End)			-	
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	Test	Group	s (a)									
Test of Examination	1	2	3	4	5	6	7	8	9	10	11	
	Test	Seque	nce (b)	•					1			
Examination of Product	1,7	1,5	1,5	1,5	1,5	1,5	1,6	1	1	1	1	
Termination Resistance, Dry Circuit	2,6	2,4	2,4	2,4	2,4	2,4	2,5					
Dielectric Withstanding Voltage								2.5	3	3	3	
Insulation Resistance								3,6				
Temperature Rise vs Current									2			
Vibration							3					
Physical Shock							4					
Mating Force	3											
Unmating Force	4											
Durability	5											
Solderability								4			2	
Resistance to Soldering Heat										2		
Thermal Shock			3									
Humidity- Temperature Cycling		3										
Corrosin, Salt Spray						3	1		1			
Temperature Life				3								
Sulfurous acid gas					3							
Number of Samples	5	3	3	3	3	3	3	3	3	3	10	

3.6 Product Qualification and Requalification Tests.

(a) Numbers indicate sequence in which tests are performed.

Fig.2

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Fig. 4

Product Part No.	Description
X-5175610-X	Plug Connector, Horizontal Type, W/O Retention Leg.
X-5175472-X	Plug Connector, Horizontal Type, with Retention Leg.
X-5175611-X	Plug Connector, Vertical Type, W/O Retention Leg.
X-5175473-X	Plug Connector, Vertical Type, with Retention Leg.
X-5175612-X	Receptacle Connector, Horizontal Type, W/O Retention Leg.
X-5175474-X	Receptacle Connector, Horizontal Type, with Retention Leg.
X-5175613-X	Receptacle Connector, Vertical Type, W/O Retention Leg.
X-5175475-X	Receptacle Connector, Vertical Type, with Retention Leg.

NOTE: Prefix and suffix numbers vary depending on the variations of the number of contacts and plating designation.

Appendix 1

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